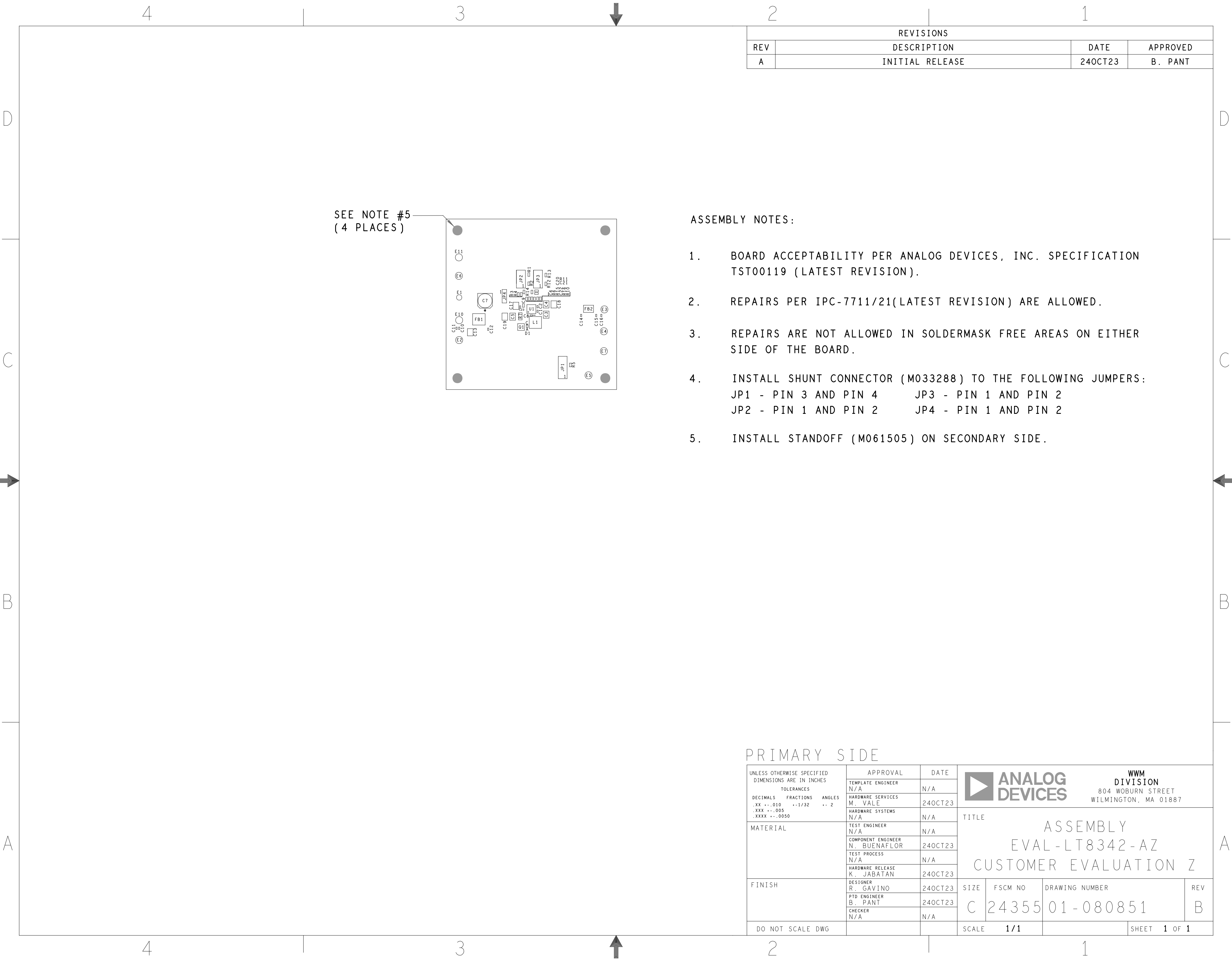


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	24OCT23	B. PANT

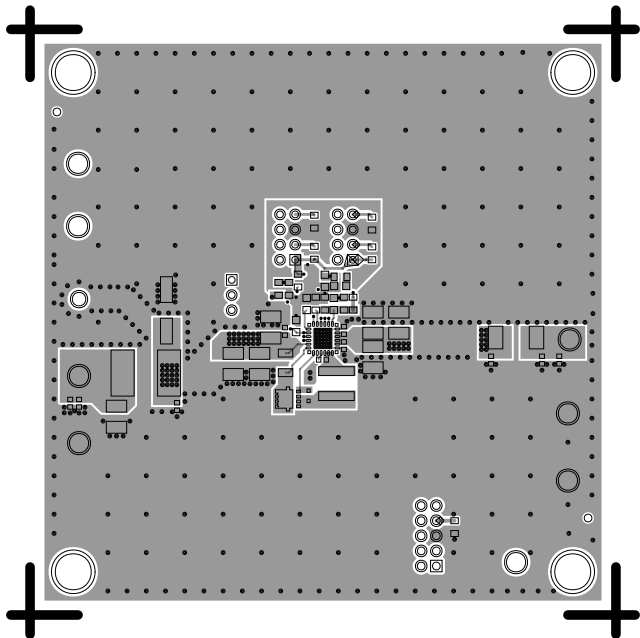
HOLE TOLERANCE  
UNLESS SPECIFIED  
PLATED: +/- .003  
NON PLATED: +/- .001

FINISHED HOLES IN MILS				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
•	6.0	PLATED	20	
◻	8.0	PLATED	30	
◦	10.0	PLATED	441	
◊	35.0	PLATED	19	
△	40.0	PLATED	10	
◻	70.0	PLATED	1	
○	100.0	PLATED	8	
A	187.0	NON-PLATED	4	

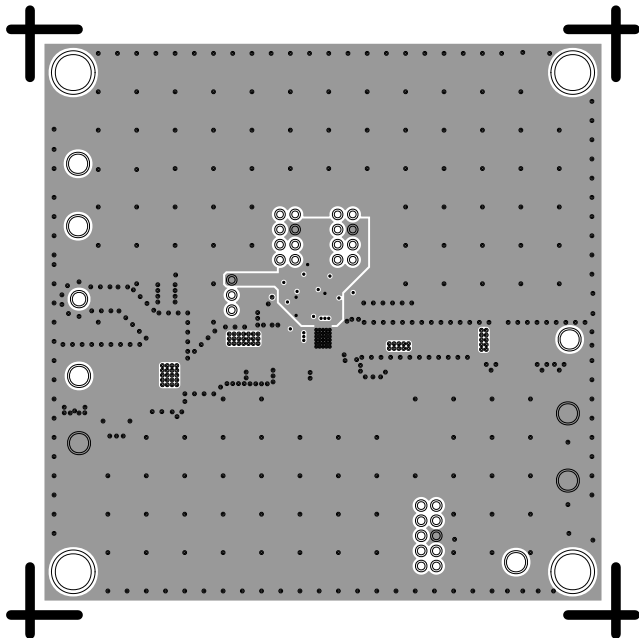
PRIMARY SIDE			ANALOG DEVICES				WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887							
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS    FRACTIONS    ANGLES .XX    .010    .1/32    .2 .XXX    .005 .XXXX    .0050			APPROVAL		DATE		TITLE  FABRICATION EVAL-LT8342-AZ CUSTOMER EVALUATION Z							
			TEMPLATE ENGINEER N/A		N/A									
			HARDWARE SERVICES M. VALE		24OCT23									
			HARDWARE SYSTEMS N/A		N/A									
MATERIAL			TEST ENGINEER N/A		N/A		SIZE C		FSCM NO 24355		DRAWING NUMBER 09-080851		REV B	
			COMPONENT ENGINEER N. BUENAFLO		24OCT23									
			TEST PROCESS N/A		N/A									
			HARDWARE RELEASE K. JABATAN		24OCT23									
FINISH			DESIGNER R. GAVINO		24OCT23		SCALE 1/1		SHEET 1 OF 2					
			PTD ENGINEER B. PANT		24OCT23									
			CHECKER N/A		N/A									
DO NOT SCALE DWG														



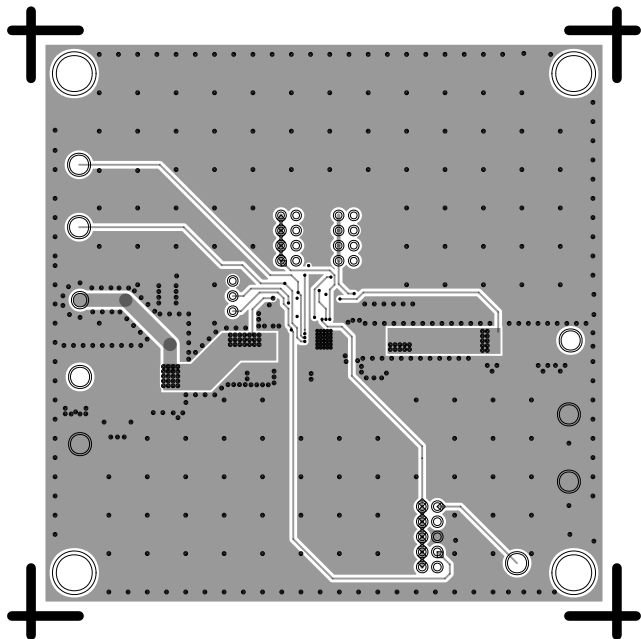
L1 PRIMARY  
08-080851-01  
REV B



L2 GND  
08-080851-06  
REV B



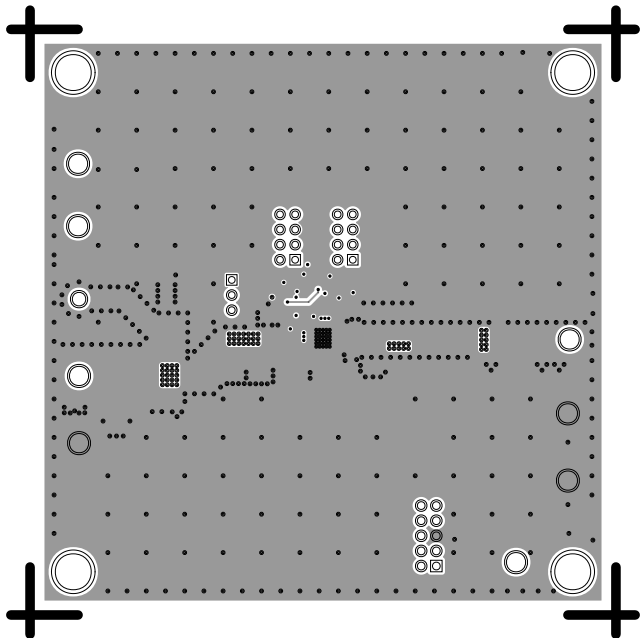
L3 GND  
08-080851-07  
REV B



L4 SECONDARY

08-080851-02

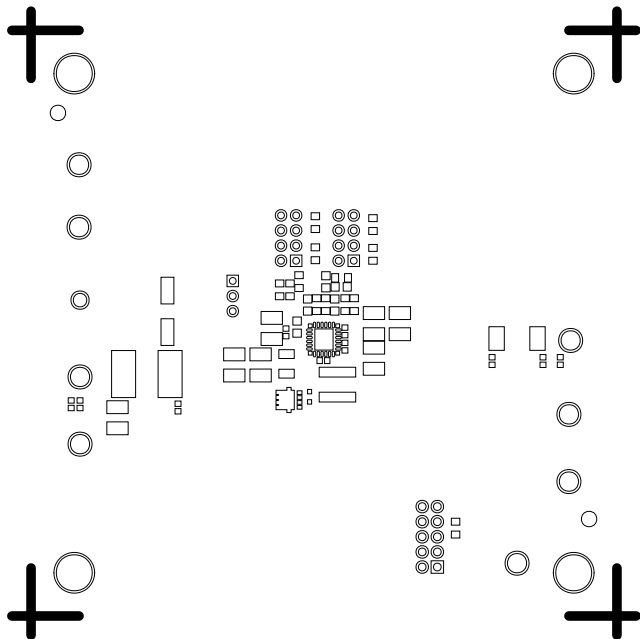
REV B



SOLDERMASK PRIMARY

08-080851-04

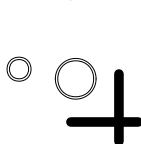
REV B



SOLDERMASK SECONDARY

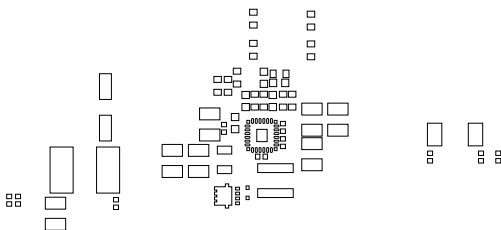
08-080851-05

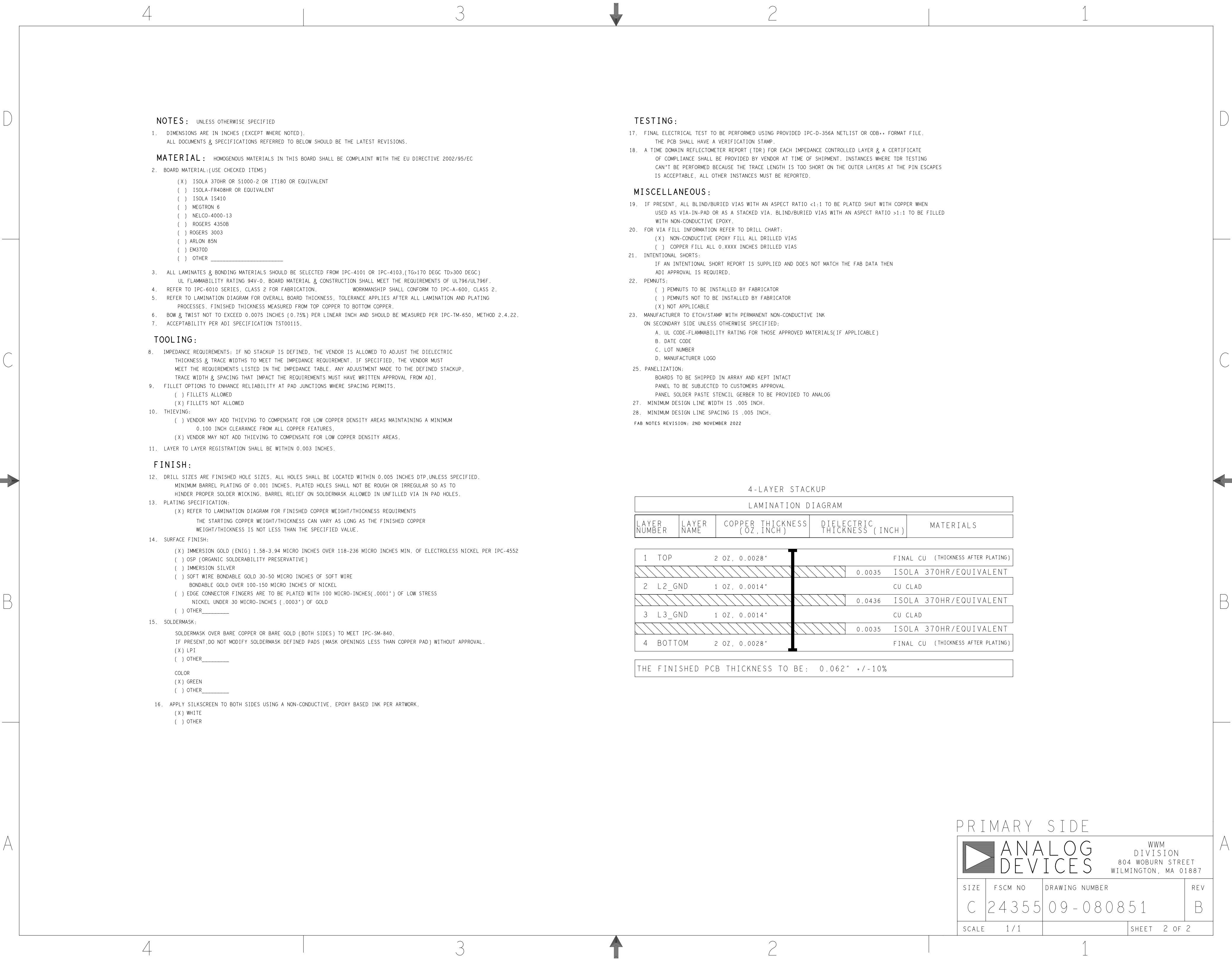
REV B





PASTEMASK PRIMARY  
08-080851-9  
REV B





NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).  
ALL DOCUMENTS & SPECIFICATIONS REFERRED TO BELOW SHOULD BE THE LATEST REVISIONS.

MATERIAL: HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLAINT WITH THE EU DIRECTIVE 2002/95/EC

2. BOARD MATERIAL:(USE CHECKED ITEMS)
- ☒

ISOLA 370HR OR SI000-2 OR IT180 OR EQUIVALENT
- ☐

ISOLA-FR408HR OR EQUIVALENT
- ☐

ISOLA IS410
- ☐

MEGTRON 6
- ☐

NELCO-4000-13
- ☐

ROGERS 4350B
- ☐

ROGERS 3003
- ☐

ARLON 85N
- ☐

EM370D
- ☐

OTHER \_\_\_\_\_

TOOLING:

8. IMPEDANCE REQUIREMENTS: IF NO STACKUP IS DEFINED, THE VENDOR IS ALLOWED TO ADJUST THE DIELECTRIC THICKNESS & TRACE WIDTHS TO MEET THE IMPEDANCE REQUIREMENT. IF SPECIFIED, THE VENDOR MUST MEET THE REQUIREMENTS LISTED IN THE IMPEDANCE TABLE. ANY ADJUSTMENT MADE TO THE DEFINED STACKUP, TRACE WIDTH & SPACING THAT IMPACT THE REQUIREMENTS MUST HAVE WRITTEN APPROVAL FROM ADI.
9. FILLET OPTIONS TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS.  
( ) FILLETS ALLOWED  
(X) FILLETS NOT ALLOWED
10. THIEVING:  
( ) VENDOR MAY ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS MAINTAINING A MINIMUM 0.100 INCH CLEARANCE FROM ALL COPPER FEATURES.  
(X) VENDOR MAY NOT ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS.
11. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003 INCHES.

FINISH:

12. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN 0.005 INCHES DTP,UNLESS SPECIFIED.  
MINIMUM BARREL PLATING OF 0.001 INCHES. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING. BARREL RELIEF ON SOLDERMASK ALLOWED IN UNFILLED VIA IN PAD HOLES.
13. PLATING SPECIFICATION:  
(X) REFER TO LAMINATION DIAGRAM FOR FINISHED COPPER WEIGHT/THICKNESS REQUIRMENTS  
THE STARTING COPPER WEIGHT/THICKNESS CAN VARY AS LONG AS THE FINISHED COPPER WEIGHT/THICKNESS IS NOT LESS THAN THE SPECIFIED VALUE.
14. SURFACE FINISH:  
(X) IMMERSION GOLD (ENIG) 1.58-3.94 MICRO INCHES OVER 118-236 MICRO INCHES MIN. OF ELECTROLESS NICKEL PER IPC-4552  
( ) OSP (ORGANIC SOLDERABILITY PRESERVATIVE)  
( ) IMMERSION SILVER  
( ) SOFT WIRE BONDABLE GOLD 30-50 MICRO INCHES OF SOFT WIRE  
BONDABLE GOLD OVER 100-150 MICRO INCHES OF NICKEL  
( ) EDGE CONNECTOR FINGERS ARE TO BE PLATED WITH 100 MICRO-INCHES(.0001") OF LOW STRESS NICKEL UNDER 30 MICRO-INCHES (.0003") OF GOLD  
( ) OTHER \_\_\_\_\_
15. SOLDERMASK:  
SOLDERMASK OVER BARE COPPER OR BARE GOLD (BOTH SIDES) TO MEET IPC-SM-840.  
IF PRESENT,DO NOT MODIFY SOLDERMASK DEFINED PADS (MASK OPENINGS LESS THAN COPPER PAD) WITHOUT APPROVAL.  
(X) LPI  
( ) OTHER \_\_\_\_\_  
  
COLOR  
(X) GREEN  
( ) OTHER \_\_\_\_\_
16. APPLY SILKSCREEN TO BOTH SIDES USING A NON-CONDUCTIVE, EPOXY BASED INK PER ARTWORK.  
(X) WHITE  
( ) OTHER

TESTING:

17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE.  
THE PCB SHALL HAVE A VERIFICATION STAMP.
18. A TIME DOMAIN REFLECTOMETER REPORT (TDR) FOR EACH IMPEDANCE CONTROLLED LAYER & A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TDR TESTING CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES IS ACCEPTABLE, ALL OTHER INSTANCES MUST BE REPORTED.

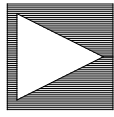
MISCELLANEOUS:

19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY.
20. FOR VIA FILL INFORMATION REFER TO DRILL CHART:  
(X) NON-CONDUCTIVE EPOXY FILL ALL DRILLED VIAS  
( ) COPPER FILL ALL 0.XXXX INCHES DRILLED VIAS
21. INTENTIONAL SHORTS:  
IF AN INTENTIONAL SHORT REPORT IS SUPPLIED AND DOES NOT MATCH THE FAB DATA THEN ADI APPROVAL IS REQUIRED.
22. PEMNUTS:  
( ) PEMNUTS TO BE INSTALLED BY FABRICATOR  
( ) PEMNUTS NOT TO BE INSTALLED BY FABRICATOR  
(X) NOT APPLICABLE
23. MANUFACTURER TO ETCH/STAMP WITH PERMANENT NON-CONDUCTIVE INK  
ON SECONDARY SIDE UNLESS OTHERWISE SPECIFIED:  
A. UL CODE-FLAMMABILITY RATING FOR THOSE APPROVED MATERIALS(IF APPLICABLE)  
B. DATE CODE  
C. LOT NUMBER  
D. MANUFACTURER LOGO
25. PANELIZATION:  
BOARDS TO BE SHIPPED IN ARRAY AND KEPT INTACT  
PANEL TO BE SUBJECTED TO CUSTOMERS APPROVAL  
PANEL SOLDER PASTE STENCIL GERBER TO BE PROVIDED TO ANALOG
27. MINIMUM DESIGN LINE WIDTH IS .005 INCH.
28. MINIMUM DESIGN LINE SPACING IS .005 INCH.

FAB NOTES REVISION: 2ND NOVEMBER 2022

4-LAYER STACKUP				
LAMINATION DIAGRAM				
LAYER NUMBER	LAYER NAME	COPPER THICKNESS (OZ./INCH)	DIELECTRIC THICKNESS (INCH)	MATERIALS
1	TOP	2 OZ, 0.0028"		FINAL CU (THICKNESS AFTER PLATING)
			0.0035	ISOLA 370HR/EQUIVALENT
2	L2_GND	1 OZ, 0.0014"		CU CLAD
			0.0436	ISOLA 370HR/EQUIVALENT
3	L3_GND	1 OZ, 0.0014"		CU CLAD
			0.0035	ISOLA 370HR/EQUIVALENT
4	BOTTOM	2 OZ, 0.0028"		FINAL CU (THICKNESS AFTER PLATING)
THE FINISHED PCB THICKNESS TO BE: 0.062" +/-10%				

PRIMARY SIDE

		ANALOG DEVICES		WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887	
		SIZE	FSCM NO	DRAWING NUMBER	REV
C		24355	09-080851	B	
SCALE		1 / 1		SHEET 2 OF 2	

# SILKSCREEN PRIMARY

08-080851-03

REV B

## LT8342

LOW IQ BOOST CONVERTER WITH 9A, 40V SWITCH  
AND OUTPUT SHORT CIRCUIT PROTECTION  
EVAL-LT8342-AZ

